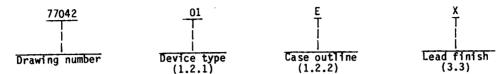
1	CC	NPF

1.1 <u>Scope</u>. This drawing describes the requirements for monolithic silicon, low-power Schottky TTL, 4 X 4 register file microcircuits. This drawing provides for a level of microcircuit quality and reliability assurance for acquisition of microcircuits in accordance with MIL-M-38510.

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device type. The device type shall identify the circuit function as follows:

Device type Generic number Circuit

O1 54LS670 4 X 4 register file with 3-state outputs

1.2.2 <u>Case outlines</u>. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter

E D-2 (16-lead, 1/4" X 7/8"), dual-in-line package F-5 (16-lead, 1/4" X 3/8"), flat package

1.3 Absolute maximum ratings.

1.4 Recommended operating conditions.

I/ Must withstand the added P_D due to short circuit test (e.g., I_{OS}).

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO

SIZE CODE IDENT. NO. DWG NO. 77042

REV F PAGE 2



2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MTL-M-38510

Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with MIL-M-38510, and as specified herein. The country of manufacture requirement of MIL-M-38510 does not apply.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
- 3.2.1 Design documentation. The design documentation shall be in accordance with MIL-M-38510 and, unless otherwise specified in the contract or purchase order, shall be retained by the manufacturer but be available for review by the acquiring activity or contractor upon request.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
 - 3.2.3 Truth table. The truth table shall be as specified on figure 2.
 - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2.
 - 3.3 Lead material and finish. The lead material and finish shall be in accordance with MIL-M-38510.
- 3.4 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.5 Marking. Marking shall be in accordance with MIL-M-38510 except the part number shall be in accordance with 1.2 herein. The Vendor Similar Part Number may also be marked in accordance with 6.8 herein. Both part numbers, when used, shall be printed on the same surface. The "M38510/XXXYY" part number and the "JAN" or "J" mark shall not be used. Lead finish letter "X" is used only as specified in MIL-M-38510 and shall not be marked on the microcircuit or its packaging. The country of origin shall be marked on the microcircuit.
- 3.6 Quality assurance requirements. Microcircuits furnished under this drawing shall have been subjected to, and passed all the requirements, tests, and inspections detailed herein including screening and quality conformance inspections.

DEFENSE ELECTRONICS SUPPLY CENTER	SIZE A	14933	DWG NO	77042	
DAYTON, OHIO		REV F	·	PAGE	3

	1	TABLE I. Ele		erformance characte				
Test	Symbol	l un1	-55°C < T	nditions C ≤ +125°C wise specified	Group A subgroups 	·	mits Max	Unit
High-level output voltage	V _{OH}	T	; V _{TN} = 0	.7 V or 2.0 V	1, 2, 3	2.4		V
Low-level output voltage	I V _{OL}	V _{CC} = 4.5 V I _{OL} = 4 mA	; V _{IN} = 0	.7 V or 2.0 V	1, 2, 3	 	0.4	 Y
Input clamp voltage	AIC	V _{CC} = 4.5 V T _C = +25°C	; I _{IN} = -	18 mA	1,	 	-1.5	 V
High-level input current	IIH	V _{CC} = 5.5 V V _{IH} = 2.7 V	W	ny D, R, or W rite enable ead enable	1, 2, 3		20 40 60	μA Γ
Low-level input current	IIL	Y _{CC} = 5.5 V Y _{IL} = 0.4 V	A W	ny D, R, or W rite enable	1, 2, 3		-0.4 -0.8	mA
Short-circuit output current	105	 V _{CC} = 5.5 V		ead enable	1, 2, 3	-15	-1.2 -130	l I mA
Supply current	I	V _{CC} = 5.5 V			1, 2, 3	 	50	mA
Functional tests	<u> </u> 	See 4.4.1c			7			
Propagation delay time, from	t _{PLH1}	V _{CC} = 5.0 V R _L = 2 kΩ ±		= 15 pF ±10%	j 9	j i	40	ns
read select to any 0 <u>2</u> /	! ! !				10, 11		56	ns
	! !		c.	= 50 pF ±10%	9		45	ns
	1 []	 <u> </u>	 		10, 11		63	ns
	tPHL1		CL	= 15 pF ±10%	9		45	ns
	! !	 	 		10, 11		63 	ns
	[] [ICL :	= 50 pF ±10%	9	! 	50 i	ns
	! ! !	 	 		10, 11		70 	ns
ee footnotes at end	d of tabl	е.						
DEFENSE ELECTRON		PLY CENTER	SIZE A	14933	DWG NO.	12		
UAYIU	N, OHIO			REV F	PAGE	<u> </u>		

	TABLE I	. Electrical per	rformance characteristics	-			
Test	 Symbol 	-55°(unless (Conditions C < T _C < +125°C otherwise specified	Group A subgroups 	Min I	Max	Unit
Propagation delay time, from write	 t _{PLH2}	V _{CC} = 5.0 V R _L = 2 kΩ ±5%		9	 	45 	l ns
enable to any Q	 	-	 	10, 11	 	63	l ns
	 	 	C _L = 50 pF ±10%	9		50	ns
_	 	1 <u> </u>		10, 11		70	ns
	r tpHL2] 	C _L = 15 pF ±10%	9		50	ns
	i !	 	 	10, 11		70	ns
	 		 C _L = 50 pF ±10%	9] 	55	ns
	 	<u> </u> 		10, 11	i .	77	ns
Propagation delay t time, from data	l t _{PLH3}		C _L = 15 pF ±10%	9		45	ns
to any Q <u>2</u> /	 !	 		10, 11		63	ns
	 -	! !	C _L = 50 pF ±10%	9		50	l ns
_	 	 - -		10, 11		70	ns
	t _{PHL3}	 	C _L = 15 pF ±10%	9		40	ns
	 	 		10, 11	 	56	ns
	 	i 	C _L = 50 pF ±10%	9 1	:] 	45 I	ns

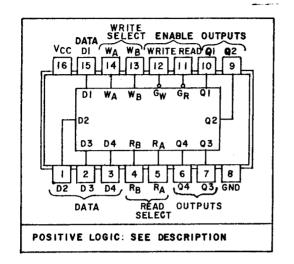
^{1/} Not more than one output should be shorted at a time and the duration of the short circuit condition should not exceed 1 second.

^{2/} Propagation delay time testing may be performed using either $C_L=15$ pF or $C_L=50$ pF. However, the manufacturer must certify and guarantee that the microcircuits meet the switching test limits specified for a 50 pF load.

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE	14933	DWG NO. 77042
		REV F	PAGE 5

10, 11

ns



logic: Low input to load sets $Q_A = A$, $Q_B = B$, $Q_C = C$, and $Q_D = D$.

FIGURE 1. Terminal connections (top view).

WRITE FUNCTION TABLE (SEE NOTES 1, 2, AND 3)

W	RITE	INP	UTS	WORD					
	₩ _B	WA	GW	0	1	2	3		
	L	L.	L	Q = D	Q ₀	Q _O	Q _O		
	L	Н	L	Q ₀	Q = D	Q_0	q_0		
	Н	L	L	Q _O	Q_{0}	Q = D	Q_0		
	Н	Н	L	Q _O	Q_0	Q_0	Q = D		
L	Х	X	Н	Q ₀	Q _O	Q _O	Q _O		

READ FUNCTION TABLE (SEE NOTES 1 AND 4)

READ	INP	UTS				
R _B	RA	GR	ſĢ	Q2	Q3	Q4
L	L	L	WOB1	WOB2	WOB3	WOB4
L	Н	L	WIBI	W1B2	W1B3	W1B4
Н	L	L	W2B1	W2B2	W2B3	W2B4
Н	Н	L	W3B1	W3B2	W3B3	W3B4
X	X	Н	Z	Z	Z	Z
	R _B L L H	R _B R _A L L L H H L H H	L L L L H L H L L H H L	R _B R _A G _R Q1 L L L W0B1 L H L W1B1 H L L W2B1 H H L W3B1	R _B R _A G _R Q1 Q2 L L L W0B1 W0B2 L H L W1B1 W1B2 H L L W2B1 W2B2 H H L W3B1 W3B2	RB RA GR Q1 Q2 Q3 L L L W0B1 W0B2 W0B3 L H L W1B1 W1B2 W1B3 H L L W2B1 W2B2 W2B3 H H L W3B1 W3B2 W3B3

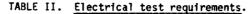
- 1. H = high level, L = low level, X = irrelevant, Z = high impedance (off).
- (Q = D) = The four selected internal flip-flop outputs will assume the states applied to the four external data inputs. Q_0 = The level of Q before the indicated input conditions were established.
- 4. WOB1 = The first bit of word 0, ect.

FIGURE 2. Truth table.

CODE IDENT, NO. SIZE DWG NO. 77042 14933 DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, ONIO REV PAGE 6 DESC FORM 144 A

- 3.6.1 <u>Screening</u>. Screening shall be in accordance with method 5004, class B, of MIL-STD-883 and 4.2 herein.
- 3.6.2 Qualification. Qualification inspection for the device type specified herein shall not be required.
- 3.6.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-38510 and 4.4 herein.
- 3.6.4 Burn-in test circuit documentation. The burn-in test circuit documentation shall be made available to the acquiring activity on request.
- 3.7 Manufacturer eligibility. To be eligible to supply microcircuits to this drawing, a manufacturer shall have manufacturer certification in accordance with MIL-M-38510 for at least one line and have part I listing on Qualified Products List QPL-38510 for at least one device type (not necessarily the one for which the acquisition of this drawing is to apply).
- 3.8 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply (see 6.7 and 6.8).
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-M-38510 and method 5005 of MIL-STD-883, except as modified herein.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria ishall apply:
 - a. Burn-in test (method 1015 of MIL-STD-883).
 - (1) Test condition A, B, C, or D.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
 - c. The percent defective allowable (PDA) shall be as specified in MIL-M-38510.
- 4.3 Qualification inspection. Qualification inspection for the device type specified herein shall not be required.
- 4.4 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-38510 and method 5005 of MIL-STD-883. Groups A and B inspections shall be performed on each inspection lot or as specified in method 5005 of MIL-STD-883. Groups C and D shall be performed on a periodic basis in accordance with MIL-M-38510. Generic test data (see 6.5) may be used to satisfy the requirements for groups C and D inspections. Manufacturers shall keep lot records for 5 years (minimum), monitor for compliance to the prescribed procedures, and observe that satisfactory manufacturing conditions and records on lots are maintained for these devices. The records, including an attributes summary of all screening and quality conformance inspections conducted on each lot shall be available for review by customers at all times.

DEFENSE ELECTRONICS SUPPLY CENTER	SIZE	14933	DWG NO. 77042	
DAYTON, OHIO		REV F	PAGE	7



MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004) 	
Final electrical test parameters (method 5004)	1*, 2, 3, 9
Group A test requirements (method 5005)	1, 2, 3, 7, 9
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3
Additional electrical subgroups for group C periodic inspections	10, 11**

- * PDA applies to subgroup 1 (see 4.2c).
 ** Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.
- 4.4.1 Group A inspection. Group A inspection shall consist of the test subgroups and LTPD values shown in table I of method 5005 of MIL-STD-883, class B, and as follows:
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 4, 5, 6, and 8 of table I of method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 7 tests shall verify the truth table.
- 4.4.2 Group B inspection. Group B inspection shall consist of the test subgroups and LTPD values shown in table IIb of method 5005 of MIL-STD-883, class B.
- 4.4.3 Groups C and D inspections. Groups C and D inspections shall consist of the test subgroups and LTPD values shown in tables III and IV, method 5005 of MIL-STD-883, class B, and as follows:
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - (1) Test condition A, B, C, or D.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE CODE IDENT. NO. 14933		DWG NO. 77042		
		REV F	PAGE 8		



- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
- 6. NOTES
- 6.1 Notes. Only the note "Reevaluation of lot quality" of the notes specified in MIL-M-38510 shall apply to this drawing.
- 6.2 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. This drawing is intended exclusively to prevent the proliferation of unnecessary duplicate specifications, drawings, and stock catalog listings. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, this drawing will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
 - 6.3 Ordering data. The contract or purchase order should specify the following:
 - a. Complete part number (see 1.2).
 - b. Requirements for delivery of one copy of the quality conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.
 - c. Requirements for certificate of compliance, if applicable.
 - d. Requirements for notification of change of product or process to the contracting activity, if applicable.
 - e. Requirements for special carriers, lead lengths, or lead forming, if applicable. These requirements shall not affect the part number. Unless otherwise specified, these requirements will not apply to direct shipment to the Government.
 - 6.4 Replaceability. Replaceability is determined as follows:
 - a. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
 - b. When a QPL source is established, the part numbered device specified in this drawing will be replaced by the microcircuit identified as part number M38510/31901B--.
- 6.5 Generic test data. Generic test data may be used to satisfy the requirements of 4.4.3. Group C generic test data shall be on date codes no more than 1 year old and on a die in the same microcircuit group (see appendix E of MIL-M-38510) with the same material, design, and process and from the same plant as the die represented. Group D generic data shall be on date codes no more than 1 year old and on the same package type (terms, definitions, and symbols of MIL-M-38510) and from the same plant as the package represented. The vendor is required to retain the generic data for a period of not less than 5 years from the date of shipment.
- 6.6 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, OH 45444, or telephone 513-296-5375.
- 6.7 Submission of certificate of compliance. The certificate of compliance submitted to DESC-ECS, prior to listing as an approved source of supply in 6.8, shall state that the manufacturer's product meets the requirements herein.

DEFENSE ELECTRONICS SUPPLY CENTER	SIZE	CODE I	933	NO.		7042	
DAYTON, OHIO		F	REV	F	P	AGE	9

APR 83

6.8 Approved sources of supply. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.8) has been submitted to DESC-ECS.

DESC drawing part number	Vendor FSCM number	Vendor similar part number <u>1</u> /	Replacement military specification part number
7704201EX	07263 04713 27014 01295		M38510/31901BEX
7704201FX 2/	07263 04713 27014 01295		M38510/31901BFX

- 2/ Inactive for new design. Use QPL-38510 product.

Vendor FSCM number	Vendor name and address
07263	Fairchild Semiconductor 333 Western Avenue S. Portland, ME 04106
04713	Motorola, Incorporated 7402 S. Price Road Tempe, AZ 85283
27014	National Semiconductor Corporation 2900 Semiconductor Drive Santa Clara, CA 95051
01295	Texas Instruments, Incorporated P. O. Box 6448 Midland, TX 79071

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO

SIZE CODE IDENT. NO. DWG NO.

14933 77042

REV F PAGE 10